

DATASHEET

6 PIN DIP PHOTOTRANSISTOR PHOTOCOUPLER AC INPUT PHOTOCOUPLER H11AAX Series



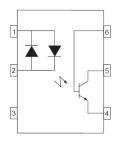




Features

- H11AAX series: H11AA1, H11AA2, H11AA3, H11AA4
- High isolation voltage between input and output Viso = 5000 Vrms
- Creepage distance >7.62 mm
- · Compact dual-in-line package
- The product itself will remain within RoHS compliant version
- Compliance with EU REACH
- UL and cUL approved(No. E214129)
- VDE approved (No.132249)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved
- CQC approved

Schematic



Pin Configuration

- 1. Anode / Cathode
- 2. Cathode / Anode
- 3. No Connection
- 4. Emitter
- 5. Collector
- 6. Base

Description

The H11AAX series of devices each consist of two infrared emitting diode, connected in inverse parallel, optically coupled to a phototransistor detector.

They are packaged in a 6-pin DIP package and available in wide-lead spacing and SMD option.

Applications

- AC line monitor
- Unknown polarity DC sensor
- Telephone line interface



Absolute Maximum Ratings (Ta=25℃)

	Parameter	Symbol	Rating	Unit
	Forward current	I _F	60	mA
loout	Peak forward current (t = 10µs)	I _{FM}	1	А
Input	Power dissipation (TA = 25°C)	D	120	mW
	Derating factor (above 90°C)	P _D —	3.8	mW/°C
	Power dissipation (T _A = 25°C) No derating up to 100°C	P _C	150	mW
Output	Collector-Emitter voltage	V_{CEO}	80	V
	Collector-Base voltage	V_{CBO}	80	V
	Emitter-Collector voltage	V_{ECO}	7	V
Total Power Dissipation		P _{TOT}	200	mW
Isolation Voltage*1		V_{ISO}	5000	V rms
Operating Temperature		T_OPR	-55 to 100	°C
Storage Temperature		T _{STG}	-55 to 125	°C
Soldering Temperature* ²		T _{SOL}	260	°C

Notes

^{*1} AC for 1 minute, R.H.= $40 \sim 60\%$ R.H. In this test, pins 1, 2 & 3 are shorted together, and pins 4, 5 & 6 are shorted together.

^{*2} For 10 seconds



Electro-Optical Characteristics (Ta=25°C unless specified otherwise)

Input

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward Voltage	V_{F}	-	1.2	1.5	V	$I_F = \pm 10 \text{mA}$
Input capacitance	C _{in}	-	80	-	pF	V = 0, f = 1MHz

Output

Parameter	Symbol	Min	Тур.	Max.	Unit	Condition
Collector-Emitter dark current	I _{CEO}	-	-	50	nA	$V_{CE} = 10V$, $I_F = 0mA$
Collector-Emitter breakdown voltage	BV_CEO	80	-	-	V	I _C = 1mA
Collector-Base breakdown voltage	BV_CBO	80	-	-	V	I _C = 0.1mA
Emitter-Collector breakdown voltage	BV _{ECO}	7	-	-	V	I _E = 0.1mA
Collector-Emitter capacitance	C _{CE}	-	10	-	pF	VCE = 0V, f = 1MHz

Transfer Characteristics

Parameter		Symbol	Min	Тур.	Max.	Unit	Condition	
	H11AA1		20	-	-	- - % -		
Current Transfer ratio	H11AA2		10	-	-		$I_F = \pm 10 \text{mA}, V_{CE} = 10 \text{V}$	
	H11AA3	CTR -	50	-	-			
	H11AA4		100	-	-			
CTR Symmetry			0.5	-	2.0		$I_F = \pm 10 \text{mA}, V_{CE} = 10 \text{V}$	
Collector-emitter saturation voltage		V _{CE(sat)}	-	-	0.4	V	$I_F = \pm 10 \text{mA}$, $I_C = 0.5 \text{mA}$	
Isolation resistance		R _{IO}	10 ¹¹	-	-	Ω	V _{IO} = 500Vdc, 40~60% R.H.	
Input-output capacitance		C_{IO}	-	0.7	-	pF	$V_{IO} = 0$, $f = 1MHz$	
Turn-on time		T _{on}	-	-	10			
Turn-off time		T_{off}	-	-	10		V _{CC} = 10V,	
Rise time		Tr	-	-	10	μs	$I_C = 10$ mA, $R_L = 100\Omega$	
Fall time		T _f	-	-	10	•		

^{*} Typical values at T_a = 25°C



Typical Electro-Optical Characteristics Curves

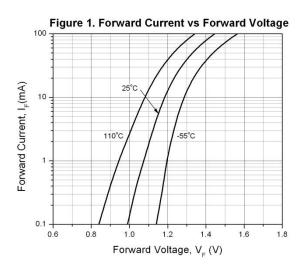


Figure 2. Current Tranfer Ratio vs Forward Current

1.2

0.6

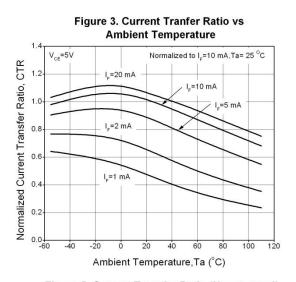
0.4

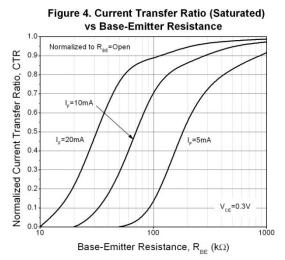
V_{ce}=5 V

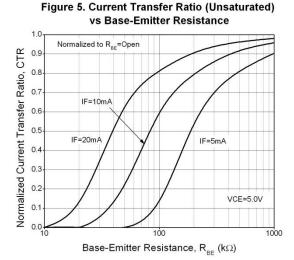
Ta=25°C

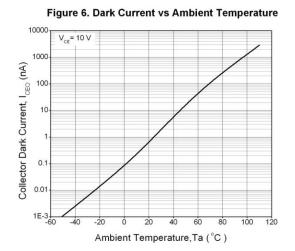
Normalized to I_F=10 mA

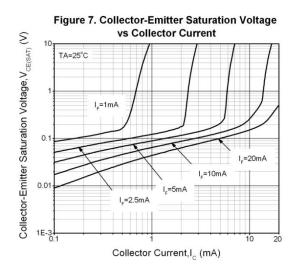
Forward Current, I_E (mA)

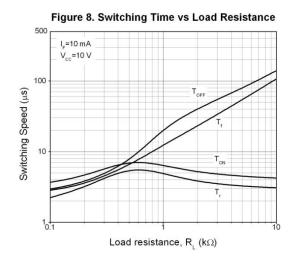


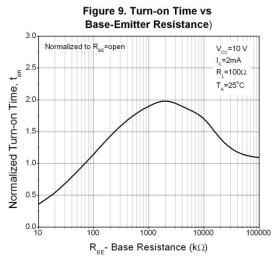


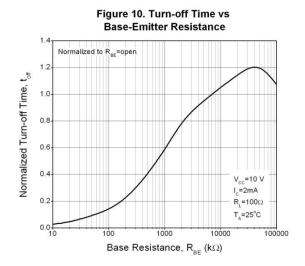


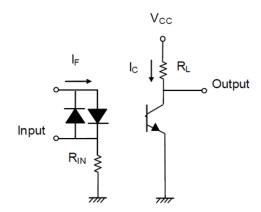












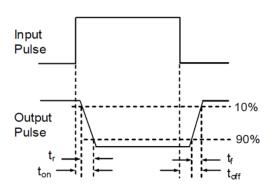


Figure 11. Switching Time Test Circuit & Waveforms



Order Information

Part Number

H11AAXY(Z)-V

Notes

Χ = CTR Rank (1, 2, 3, or 4)

= Lead form option (S, S1, M or none)

Ż V = Tape and reel option (TA, TB, or none).

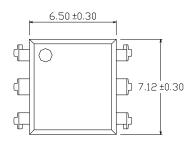
= VDE safety (optional).

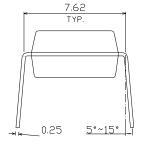
Option	Description	Packing quantity
None	Standard DIP-6	65 units per tube
М	Wide lead bend (0.4 inch spacing)	65 units per tube
S (TA)	Surface mount lead form + TA tape & reel option	1000 units per reel
S (TB)	Surface mount lead form + TB tape & reel option	1000 units per reel
S1 (TA)	Surface mount lead form (low profile) + TA tape & reel option	1000 units per reel
S1 (TB)	Surface mount lead form (low profile) + TB tape & reel option	1000 units per reel

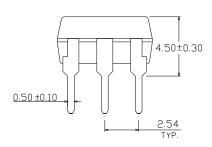


Package Dimension (Dimensions in mm)

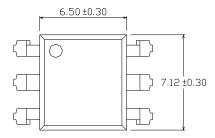
Standard DIP Type

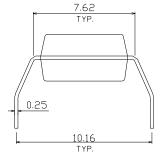


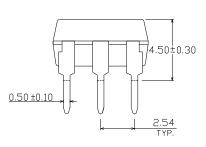




Option M Type

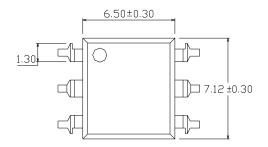


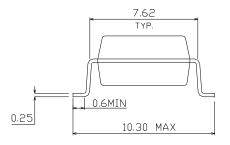


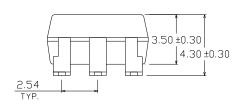




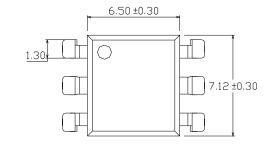
Option S Type

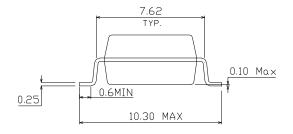


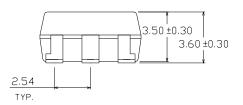




Option S1 Type

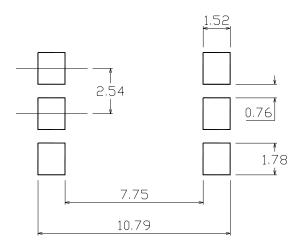








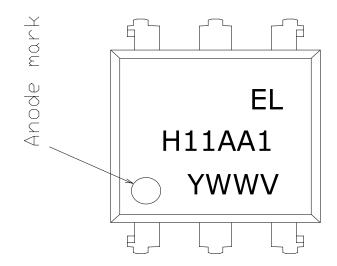
Recommended pad layout for surface mount leadform



Notes

Suggested pad dimension is just for reference only. Please modify the pad dimension based on individual need.

Device Marking

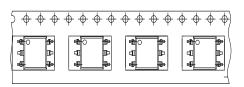


Notes

EL denotes Everlight
H11AA1 denotes Part Number
Y denotes 1 digit Year code
WW denotes 2 digit Week code
V denotes VDE safety (optional)

Tape & Reel Packing Specifications

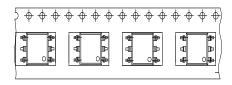
Option TA





Direction of feed from reel

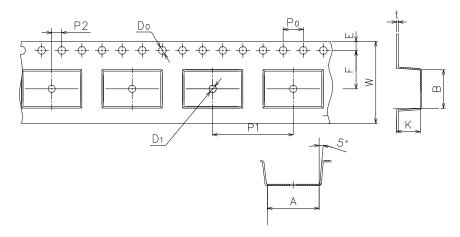
Option TB





Direction of feed from reel

Tape dimensions



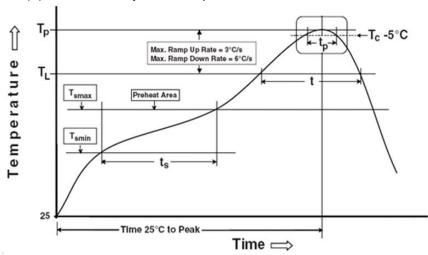
Dimension No.	Α	В	Do	D1	E	F
Dimension (mm)	10.4±0.1	7.5±0.1	1.5±0.1	1.5+0.1/-0	1.75±0.1	7.5±0.1
Dimension No.	Ро	P1	P2	t	w	К
Dimension (mm)	4.0±0.15	12±0.1	2.0±0.1	0.35±0.03	16.0±0.2	4.5±0.1



Precautions for Use

1. Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Notes Reference: IPC/JEDEC J-STD-020D

Preheat

Temperature min (T _{smin})	150 °C
Temperature max (T _{smax})	200°C
Time $(T_{smin} \text{ to } T_{smax}) (t_s)$	60-120 seconds
Average ramp-up rate (T _{smax} to T _p)	3 °C/second max

Other

Liquidus Temperature (T _L)	217 °C
Time above Liquidus Temperature (t L)	60-100 sec
Peak Temperature (T _P)	260°C
Time within 5 °C of Actual Peak Temperature: T _P - 5°C	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max.
Reflow times	3 times

4.



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